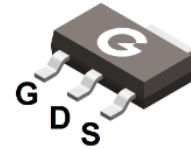
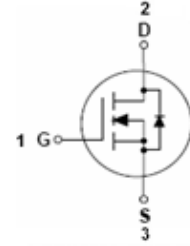


Features

- Advanced trench technology
- Low on-resistance
- Fast switching speed
- Low gate drive
- RoHS compliant with Halogen-free

HF



SOT-223

Mechanical Data

- Case: SOT-223
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matted-Tin plated; Solderable Per MIL-STD-202, Method 208

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL04N06R	SOT-223	4000 pcs / Tape & Reel	04N06

Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	60	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_A = 25^\circ\text{C}$) *1	I_D	4	A
Continuous Drain Current ($T_A = 100^\circ\text{C}$) *1		2.5	
Pulsed Drain Current ($t_p = 10\mu\text{s}$, $T_A = 25^\circ\text{C}$)	I_{DM}	20	A
Single Pulse Avalanche Energy *4	E_{AS}	9	mJ
Power Dissipation ($T_A = 25^\circ\text{C}$) *1	P_D	3.1	W
Power Dissipation ($T_A = 25^\circ\text{C}$) *2		2	
Operating Junction Temperature Range	T_J	$-55 \sim +150$	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Air *1	$R_{\theta JA}$	-	-	40.3	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air *2		-	-	62	

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V _{DS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
On Characteristics						
R _{DS(ON)}	Drain-Source On-resistance *3	V _{GS} = 10V, I _D = 4A	-	55	105	mΩ
		V _{GS} = 4.5V, I _D = 4A	-	72	125	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.8	1.6	2	V
R _G	Gate Resistance	V _{GS} = 0V, f = 1MHz	-	7.7	-	Ω
Dynamic Characteristics						
C _{ISS}	Input Capacitance	V _{GS} = 0V V _{DS} = 40V f = 1MHz	-	420	-	pF
C _{OSS}	Output Capacitance		-	23	-	
C _{RSS}	Reverse Transfer Capacitance		-	20	-	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time *5	V _{DD} = 30V V _{GS} = 10V R _G = 1Ω I _D = 1.5A	-	6.5	-	ns
t _r	Turn-on Rise Time *5		-	15.2	-	
t _{d(OFF)}	Turn-Off Delay Time *5		-	15.2	-	
t _f	Turn-Off Fall Time *5		-	10.3	-	
Q _G	Total Gate-Charge	V _{DD} = 30V V _{GS} = 10V I _D = 4A	-	8.8	-	nC
Q _{GS}	Gate to Source Charge		-	1.3	-	
Q _{GD}	Gate to Drain (Miller) Charge		-	2.1	-	
Source-Drain Diode Characteristics						
V _{SD}	Diode Forward Voltage *3	I _{SD} = 4A, V _{GS} = 0V	-	0.85	2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _F = 4A	-	14	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /d _t = 100A/μs	-	9	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t \leq 1\text{s}$
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, steady state
3. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
4. The E_{AS} data shows Max. rating. The test condition is $V_{DD} = 30\text{V}, V_{GS} = 10\text{V}, L = 0.5\text{mH}$
5. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

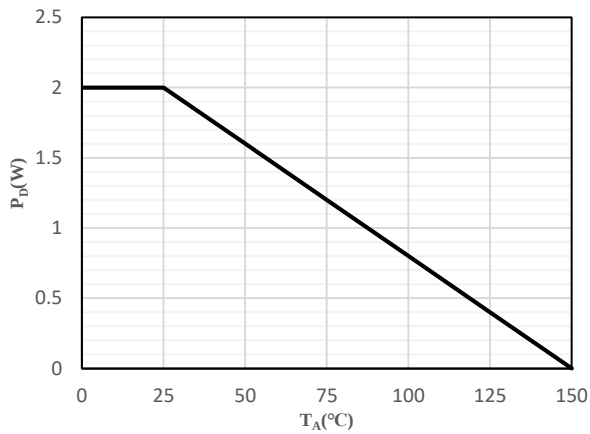


Fig 1 Power Dissipation

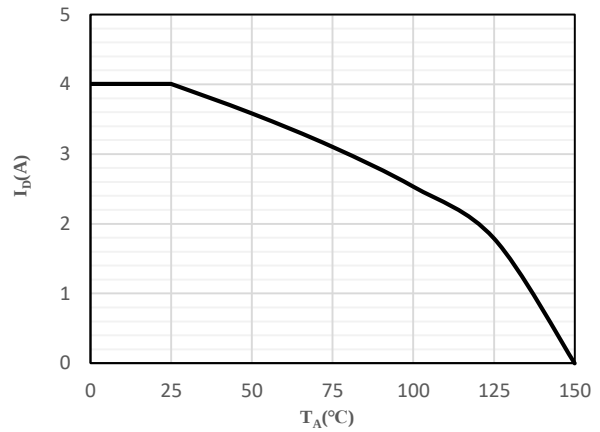


Fig 2 Drain Current

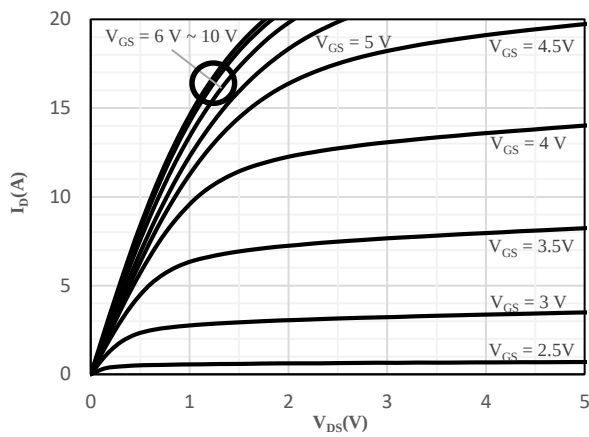


Fig 3 Typical Output Characteristics

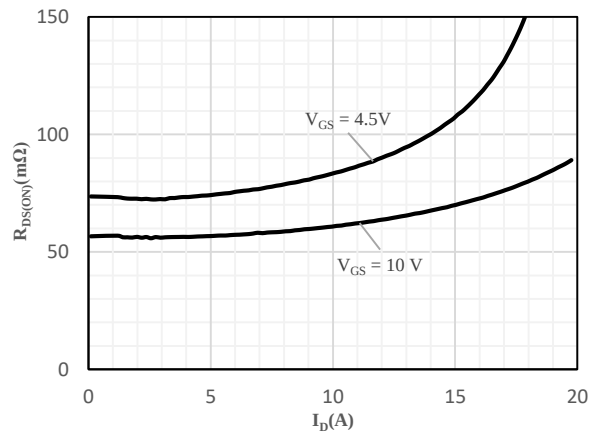


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

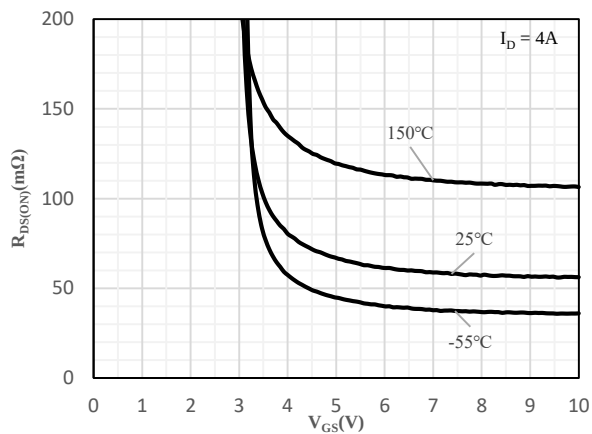


Fig 5 On-Resistance vs. Gate-Source Voltage

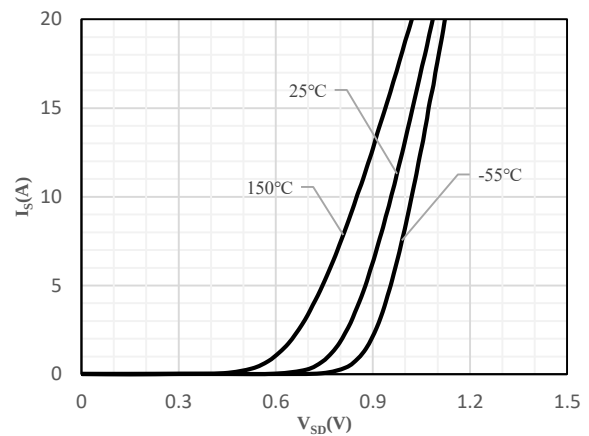


Fig 6 Body-Diode Characteristics

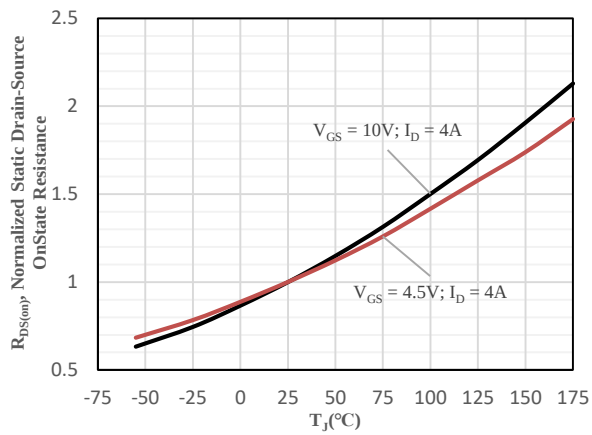


Fig 7 Normalized On-Resistance vs. Junction Temperature

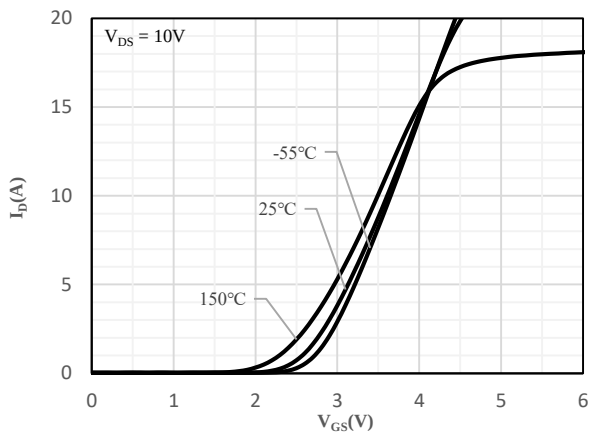


Fig 8 Transfer Characteristics

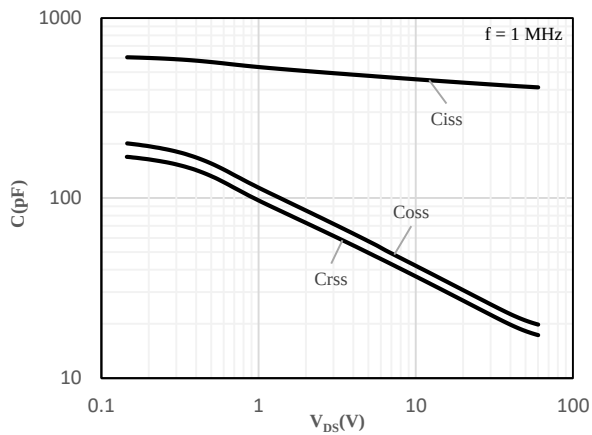


Fig 9 Capacitance Characteristics

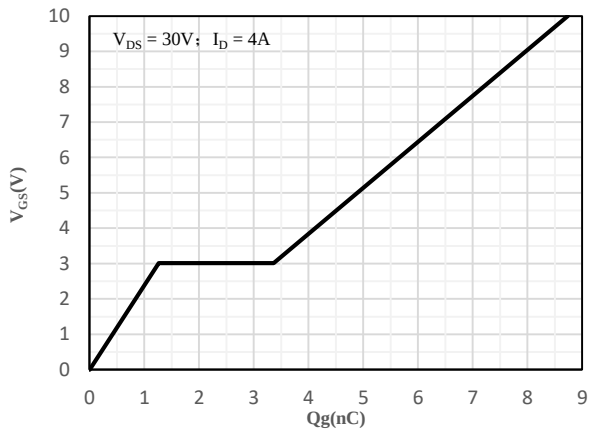


Fig 10 Gate-Charge Characteristics

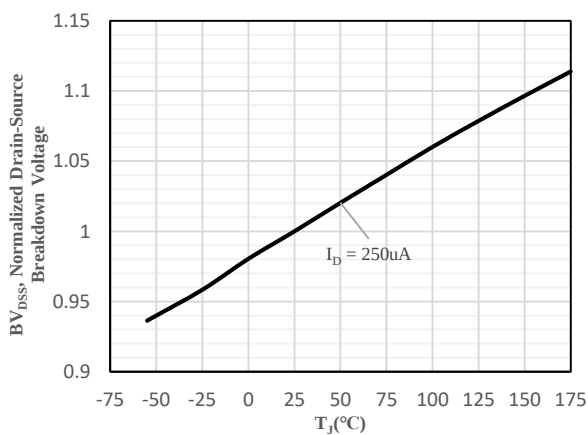


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

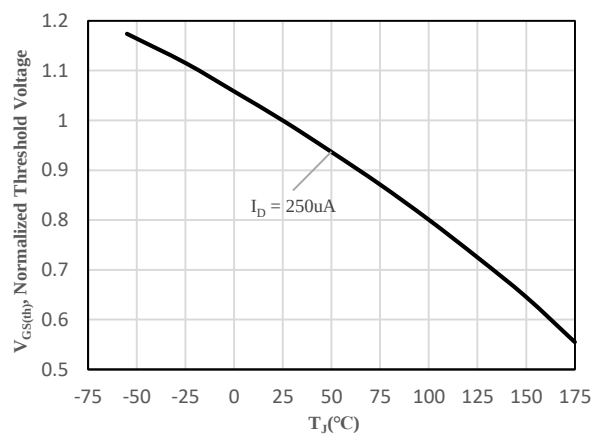


Fig 12 Normalized $V_{GS(th)}$ vs. Junction Temperature

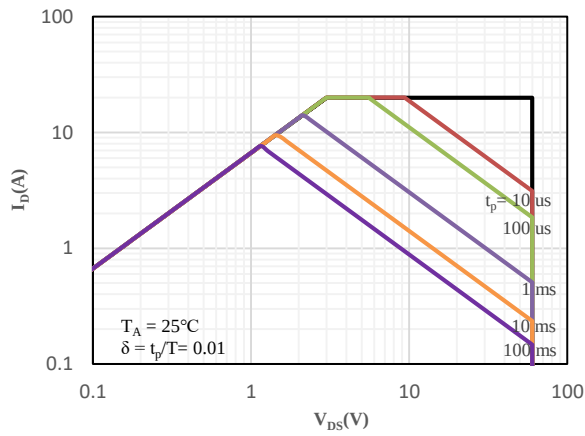


Fig 13 Safe Operating Area

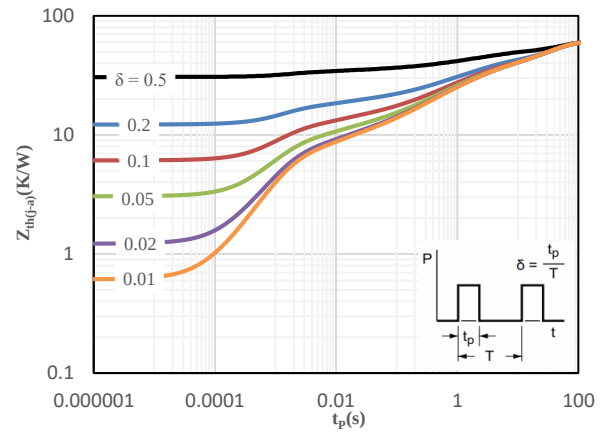
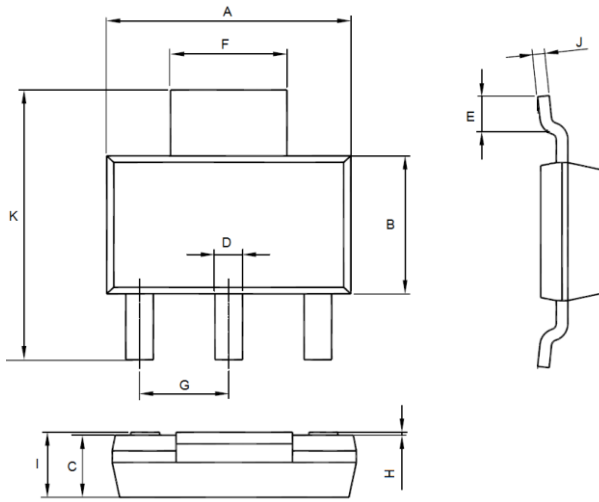


Fig 14 Maximum transient thermal impedance

Package Outline Dimensions (Unit: mm)



SOT-223		
Dimension	Min.	Max.
A	6.10	6.50
B	3.30	3.70
C	1.50	1.70
D	0.66	0.82
E	0.90	1.15
F	2.90	3.10
G	2.20	2.40
H	0.02	0.10
I	1.52	1.80
J	0.20	0.40
K	6.70	7.30

Mounting Pad Layout (Unit: mm)

SOT-223

